ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material Comp © Copyright 2005. international and Pa	IPC. Bannock	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v s all lower	within the manufactur level materials for w	rer listed ite hich the m	em. Note: anufactur	if the item is an as er has engineering	sembly with low responsibility.
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infor					g Informa	ation		
upplier Information													
Company name* Company			y unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-23			
Contact Name Title - Contact			t			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repres			sentative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Envir			riro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version Manufacturing Site		Ianufacturing Site	V	Veight*	UOM	Unit Type
	S100	100 1A 100V		100V SCHOTTKY RECT		2024-04-23		P.	PANJITFG		7.9	mg	Each
Ianufacturing Proccess Informa	ition												
Terminal Plating / Grid Array M	aterial	Ferminal Base A	lloy J-STD-020 MSL Rati		Rating	Peak Proc	Process Body Temperature		re Max Time at Peak Tempera		ire Nun	nber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	second	ls 3		
omments													
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	use indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, mium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part tains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall ompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, if the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Inpany acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not pendently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the ranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.764	mg	Supplier	Silicon (Si)	7440-21-3		0.7585	mg
			В	Nickel (Ni)	7440-02-0		0.0011	mg
			Supplier	Gold (Au)	7440-57-5		0.0042	mg
			В	Arsenic (As)	7440-38-2		0.0002	mg
Die Attach Solder	2.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0563	mg
			А	Lead (Pb)	7439-92-1	7a	2.0812	mg
			Supplier	Tin (Sn)	7440-31-5		0.1125	mg
Lead Frame	27.5903	mg	Supplier	Iron (Fe)	7439-89-6		0.0331	mg
			Supplier	Copper (Cu)	7440-50-8		27.5489	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0083	mg
Mold Compound-Black	36.69	mg		Metal Hydroxide	proprietary data		1.2842	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.9352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1834	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.352	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.9352	mg
Plating	0.6057	mg	Supplier	Tin (Sn)	7440-31-5		0.6057	mg